# Thermoplastics hot melt adhesive application for formation of smart card component layer or electronic transponder

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Abstract of **DE19848712**

The thermoplastics hot melt adhesive application has a hot melt adhesive material used for providing smart card component layers or electronic transponders, e.g. using low pressure injection molding at a pressure of between 1 and 50 bar and a temperature of between 80 and 250 degrees C. Also included are Independent claims for the following: (a) a smart card manufacturing method; and (b) a multi-layer card body.

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